

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chin-Wei Liang</td> <td>08/07/2013</td> </tr> <tr> <td>Hsing-Lien Lin</td> <td>08/07/2013</td> </tr> <tr> <td>Cheng-Yuan Tsai</td> <td>08/07/2013</td> </tr> <tr> <td>Chia-Shiung Tsai</td> <td>08/07/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chin-Wei Liang	08/07/2013	Hsing-Lien Lin	08/07/2013	Cheng-Yuan Tsai	08/07/2013	Chia-Shiung Tsai	08/07/2013
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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CORRESPONDENCE DATA											
Fax Number: 2142000853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 214-651-5000 Email: ipdocketing@haynesboone.com Correspondent Name: HAYNES AND BOONE, LLP IP Section Address Line 1: 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219											
ATTORNEY DOCKET NUMBER:	24061.2514										
NAME OF SUBMITTER:	Linda Ingram										
Signature:	/Linda Ingram/										

PATENT

Date:

08/28/2013

Total Attachments: 2

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|---|
| (1) | Chin-Wei Liang | of | 9F., No. 173, Liujia 8th Street
Zhubei City, Hsinchu County 302
Taiwan R.O.C. |
| (2) | Hsing-Lien Lin | of | No. 11, Jinshan 16th Street, Jinshan
Hsin-Chu, Taiwan, R.O.C. |
| (3) | Cheng-Yuan Tsai | of | 101, Wen-Yi Street, Chu-Pei City
Hsin-Chu County, Taiwan, R.O.C. |
| (4) | Chia-Shiung Tsai | of | No. 5, 50 Alley, 62 Lane
Gua-Tsuey Road
Hsin-Chu, Taiwan, R.O.C. |

have invented certain improvements in

ORGANIC PHOTOSENSITIVE DEVICE WITH AN ELECTRON-BLOCKING AND HOLE-TRANSPARENT LAYER

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on August 28, 2013, and assigned application number 14/012,692; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on

applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chin-Wei Liang

Residence Address: 9F., No. 173, Liujia 8th Street
Zhubei City, Hsinchu County 302, Taiwan R.O.C.

Dated: 2013/08/07

Chin Wei Liang
Inventor Signature

Inventor Name: Hsing-Lien Lin

Residence Address: No.11, Jinshan 16th Street, Jinshan, Hsin-Chu, Taiwan, R.O.C.

Dated: Hs, 2013/08/07

Hsing-Lien Lin
Inventor Signature

Inventor Name: Cheng-Yuan Tsai

Residence Address: 101, Wen-Yi Street, Chu-Pei City, Hsin-Chu County, Taiwan, R.O.C.

Dated: 2013/08/07

Cheng-Yuan Tsai
Inventor Signature

Inventor Name: Chia-Shiung Tsai

Residence Address: No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road, Hsin-Chu, Taiwan, R.O.C.

Dated: 2013/08/07

Chia Shiung Tsai
Inventor Signature